

ABSTRACT OF THE DISCLOSURE

A plating method for a printed circuit board includes: a first step of providing a substrate having a plurality of connection pads and circuit patterns
5 connected to the connection pads; a second step of using some of the circuit patterns provided on a surface of the substrate as a power connection portion and connecting the power connection portion to an external power source; a third step of covering a surface of the substrate excepting the connection pads with a plating resistance resist to shield it; a fourth step of supplying power to the connection
10 pad through the power connection portion and forming a gold-plated layer on the connection pad; and a fifth step of making the power connection portion and the external power source to be electrically short. With this method, a printed circuit board without a power supply line for gold-plating can be obtained.